

|              |   |                    |
|--------------|---|--------------------|
| $V_{RM}$     | = | 6500 V             |
| $I_{T(AV)M}$ | = | 1405 A             |
| $I_{T(RMS)}$ | = | 2205 A             |
| $I_{TSM}$    | = | $22 \times 10^3$ A |
| $V_{T0}$     | = | 1.2 V              |
| $r_T$        | = | 0.6 m $\Omega$     |

## Bi-Directional Control Thyristor

# 5STB 13N6500

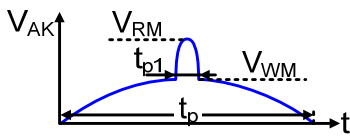
Doc. No. 5SYA1035-04 Aug. 10

- Two thyristors integrated into one wafer
- Patented free-floating silicon technology
- Designed for energy management and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

The electrical and thermal data are valid for one-thyristor-half of the device (unless otherwise stated)

### Blocking

#### Maximum rated values <sup>1)</sup>

| Parameter                                    | Symbol         | Conditions  | 5STB 13N6500 | Unit             |
|--|----------------|---|--------------|------------------|
| Max. surge peak forward blocking voltage     | $V_{SM}$       | $t_p = 10$ ms, $f = 5$ Hz<br>$T_{vj} = 5 \dots 125^\circ\text{C}$ , Note 1                                  | 6500         | V                |
| Max repetitive peak forward blocking voltage | $V_{RM}$       | $f = 50$ Hz, $t_p = 10$ ms, $t_{p1} = 250$ $\mu\text{s}$ ,<br>$T_{vj} = 5 \dots 125^\circ\text{C}$ , Note 1 | 6500         | V                |
| Max crest working forward voltages           | $V_{WM}$       |                         | 3300         | V                |
| Critical rate of rise of off-state voltage   | $dv/dt_{crit}$ | Exp. to 3750 V, $T_{vj} = 125^\circ\text{C}$  | 2000         | V/ $\mu\text{s}$ |

#### Characteristic values

| Parameter                   | Symbol     | Conditions                              | min | typ | max | Unit |
|-----------------------------|------------|---|-----|-----|-----|------|
| Max reverse leakage current | $I_{R(M)}$ | $V_{RM}$ , $T_{vj} = 125^\circ\text{C}$ |     |     | 400 | mA   |

Note 1: Voltage de-rating factor of 0.11% per  $^\circ\text{C}$  is applicable for  $T_{vj}$  below  $+5^\circ\text{C}$

Note 2: Recommended minimum ratio of  $V_{DRM} / V_{DWM}$  or  $V_{RRM} / V_{RWM} = 2$ . See App. Note 5SYA 2051.

### Mechanical data

#### Maximum rated values <sup>1)</sup>

| Parameter      | Symbol | Conditions       | min | typ | max | Unit           |
|----------------|--------|------------------|-----|-----|-----|----------------|
| Mounting force | $F_M$  |                  | 81  | 90  | 108 | kN             |
| Acceleration   | $a$    | Device unclamped |     |     | 50  | $\text{m/s}^2$ |
| Acceleration   | $a$    | Device clamped   |     |     | 100 | $\text{m/s}^2$ |

#### Characteristic values

| Parameter                 | Symbol | Conditions                              | min | typ | max  | Unit |
|---------------------------|--------|---|-----|-----|------|------|
| Weight                    | $m$    |   |     |     | 2.9  | kg   |
| Housing thickness         | $H$    | $F_M = 90$ kN, $T_a = 25^\circ\text{C}$ | 35  |     | 35.6 | mm   |
| Surface creepage distance | $D_S$  |   | 53  |     |      | mm   |
| Air strike distance       | $D_a$  |   | 22  |     |      | mm   |

1) Maximum rated values indicate limits beyond which damage to the device may occur

ABB Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.



## On-state

### Maximum rated values <sup>1)</sup>

| Parameter                         | Symbol       | Conditions   | min | typ | max                | Unit   |
|-----------------------------------|--------------|--|-----|-----|--------------------|--------|
| Average on-state current          | $I_{T(AV)M}$ | Half sine wave, $T_c = 70\text{ °C}$   |     |     | 1405               | A      |
| RMS on-state current              | $I_{T(RMS)}$ |  |     |     | 2205               | A      |
| RMS on-state current              | $I_{T(RMS)}$ | Full sine wave, $T_c = 70\text{ °C}$   |     |     | 3120               | A      |
| Peak non-repetitive surge current | $I_{TSM}$    | $t_p = 10\text{ ms}$ , $T_{vj} = 125\text{ °C}$ , sine wave after surge: $V_D = V_R = 0\text{ V}$  |     |     | $22.0 \times 10^3$ | A      |
| Limiting load integral            | $I^2t$       |  |     |     | $2.42 \times 10^6$ | $A^2s$ |
| Peak non-repetitive surge current | $I_{TSM}$    | $t_p = 8.3\text{ ms}$ , $T_{vj} = 125\text{ °C}$ , sine wave after surge: $V_D = V_R = 0\text{ V}$ |     |     | $24.0 \times 10^3$ | A      |
| Limiting load integral            | $I^2t$       |  |     |     | $2.39 \times 10^6$ | $A^2s$ |

### Characteristic values

| Parameter         | Symbol   | Conditions  | min | typ | max  | Unit      |
|-------------------|----------|---|-----|-----|------|-----------|
| On-state voltage  | $V_T$    | $I_T = 3000\text{ A}$ , $T_{vj} = 125\text{ °C}$                |     |     | 2.95 | V         |
| Threshold voltage | $V_{T0}$ | $I_T = 670\text{ A} - 2000\text{ A}$ , $T_{vj} = 125\text{ °C}$ |     |     | 1.2  | V         |
| Slope resistance  | $r_T$    |   |     |     | 0.6  | $m\Omega$ |
| Holding current   | $I_H$    | $T_{vj} = 25\text{ °C}$   |     |     | 300  | mA        |
|                   |          | $T_{vj} = 125\text{ °C}$  |     |     | 175  | mA        |
| Latching current  | $I_L$    | $T_{vj} = 25\text{ °C}$   |     |     | 500  | mA        |
|                   |          | $T_{vj} = 125\text{ °C}$  |     |     | 300  | mA        |

## Switching

### Maximum rated values <sup>1)</sup>

| Parameter                                    | Symbol         | Conditions   | min | typ | max | Unit      |
|--|----------------|--|-----|-----|-----|-----------|
| Critical rate of rise of on-state current    | $di/dt_{crit}$ | $T_{vj} = 125\text{ °C}$ ,<br>$I_{TRM} = 2000\text{ A}$ ,<br>Cont. $f = 50\text{ Hz}$  |     |     | 250 | $A/\mu s$ |
| Critical rate of rise of on-state current    | $di/dt_{crit}$ | $V_D \leq 3750\text{ V}$ ,<br>$I_{FG} = 2\text{ A}$ , $t_r = 0.5\text{ }\mu s$<br>Cont. $f = 1\text{ Hz}$  |     |     | 500 | $A/\mu s$ |
| Circuit commutated turn-off time             | $t_q$          | $T_{vj} = 125\text{ °C}$ , $I_{TRM} = 2000\text{ A}$ ,<br>$V_R = 200\text{ V}$ , $di_T/dt = -1.5\text{ A}/\mu s$ ,<br>$V_D \leq 0.67 \cdot V_{RM}$ , $dv_D/dt = 20\text{ V}/\mu s$ , | 800 |     |     | $\mu s$   |
| Critical rate of rise of commutating voltage | $dv/dt_{com}$  | $T_{vj} = 125\text{ °C}$ , $V_R \leq 0.67 \cdot V_{RM}$  |     |     | 500 | $V/\mu s$ |

### Characteristic values

| Parameter                | Symbol   | Conditions   | min  | typ | max  | Unit     |
|--------------------------|----------|--|------|-----|------|----------|
| Reverse recovery charge  | $Q_{rr}$ | $T_{vj} = 125\text{ °C}$ , $I_{TRM} = 2000\text{ A}$ ,<br>$V_R = 200\text{ V}$ , $di_T/dt = -1.5\text{ A}/\mu s$ | 2400 |     | 3800 | $\mu As$ |
| Reverse recovery current | $I_{RM}$ |  | 45   |     | 65   | A        |
| Gate turn-on delay time  | $t_{gd}$ | $T_{vj} = 25\text{ °C}$ , $V_D = 0.4 \cdot V_{RM}$ , $I_{FG} = 2\text{ A}$ ,<br>$t_r = 0.5\text{ }\mu s$         |      |     | 3    | $\mu s$  |

## Triggering

Maximum rated values <sup>1)</sup>

| Parameter                            | Symbol              | Conditions          | min        | typ | max | Unit |
|--------------------------------------|---------------------|---------------------|------------|-----|-----|------|
| Peak forward gate voltage            | V <sub>FGM</sub>    |                     |            |     | 12  | V    |
| Max. rated peak forward gate current | I <sub>FGM</sub>    |                     |            |     | 10  | A    |
| Peak reverse gate voltage            | V <sub>RGM</sub>    |                     |            |     | 10  | V    |
| Max. rated gate power loss           | P <sub>G</sub>      | For DC gate current |            |     | 3   | W    |
| Max. rated peak forward gate power   | P <sub>GM(AV)</sub> |                     | see Fig. 9 |     |     | W    |

Characteristic values

| Parameter                | Symbol          | Conditions  | min | typ | max | Unit |
|--------------------------|-----------------|---|-----|-----|-----|------|
| Gate trigger voltage     | V <sub>GT</sub> | T <sub>vj</sub> = 25 °C   |     |     | 2.6 | V    |
| Gate trigger current     | I <sub>GT</sub> | T <sub>vj</sub> = 25 °C   |     |     | 400 | mA   |
| Gate non-trigger voltage | V <sub>GD</sub> | V <sub>D</sub> = 0.4 x V <sub>RM</sub> , T <sub>vj</sub> = 125 °C | 0.3 |     |     | V    |
| Gate non-trigger current | I <sub>GD</sub> | V <sub>D</sub> = 0.4 x V <sub>RM</sub>                            | 10  |     |     | mA   |

## Thermal

Maximum rated values <sup>1)</sup>

| Parameter                            | Symbol           | Conditions | min | typ | max | Unit |
|--------------------------------------|------------------|------------|-----|-----|-----|------|
| Operating junction temperature range | T <sub>vj</sub>  |            |     |     | 125 | °C   |
| Storage temperature range            | T <sub>stg</sub> |            | -40 |     | 140 | °C   |

Characteristic values

| Parameter  | Symbol               | Conditions   | min | typ | max  | Unit |
|--|----------------------|--|-----|-----|------|------|
| Thermal resistance junction to case<br>(Valid for one thyristor half no heat flow to the second half.) | R <sub>th(j-c)</sub> | Double-side cooled<br>F <sub>m</sub> = 81...108 kN |     |     | 11.4 | K/kW |
|  | R <sub>th(j-c)</sub> | Single-side cooled<br>F <sub>m</sub> = 81...108 kN |     |     | 22.8 | K/kW |
| Thermal resistance case to heatsink  | R <sub>th(c-h)</sub> | Double-side cooled<br>F <sub>m</sub> = 81...108 kN |     |     | 2    | K/kW |
|  | R <sub>th(c-h)</sub> | Single-side cooled<br>F <sub>m</sub> = 81...108 kN |     |     | 4    | K/kW |

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

| i                     | 1      | 2      | 3      | 4      |
|-----------------------|--------|--------|--------|--------|
| R <sub>i</sub> (K/kW) | 6.770  | 2.510  | 1.340  | 0.780  |
| τ <sub>i</sub> (s)    | 0.8651 | 0.1558 | 0.0212 | 0.0075 |

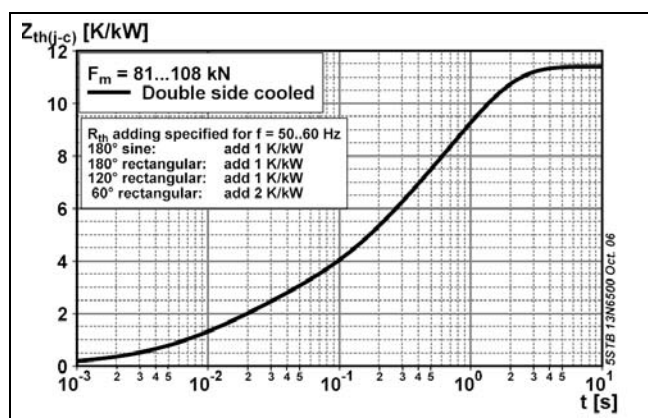
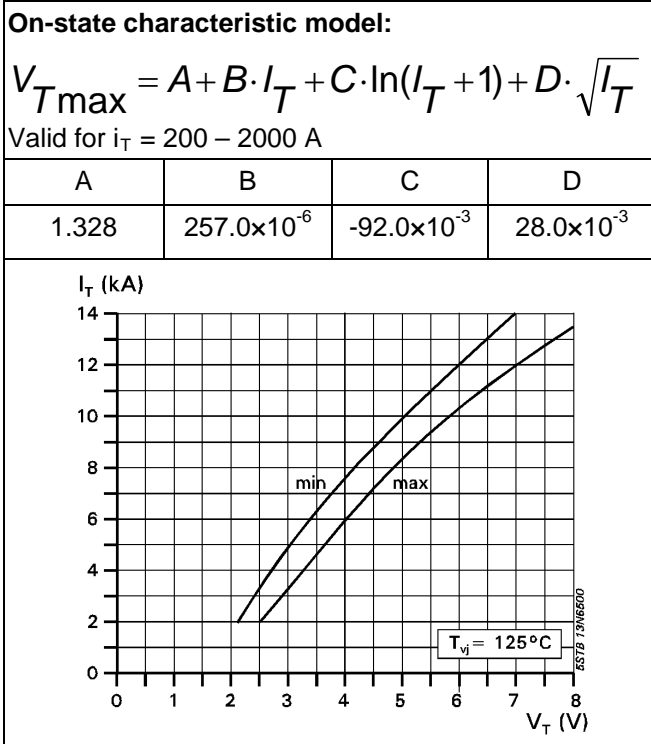
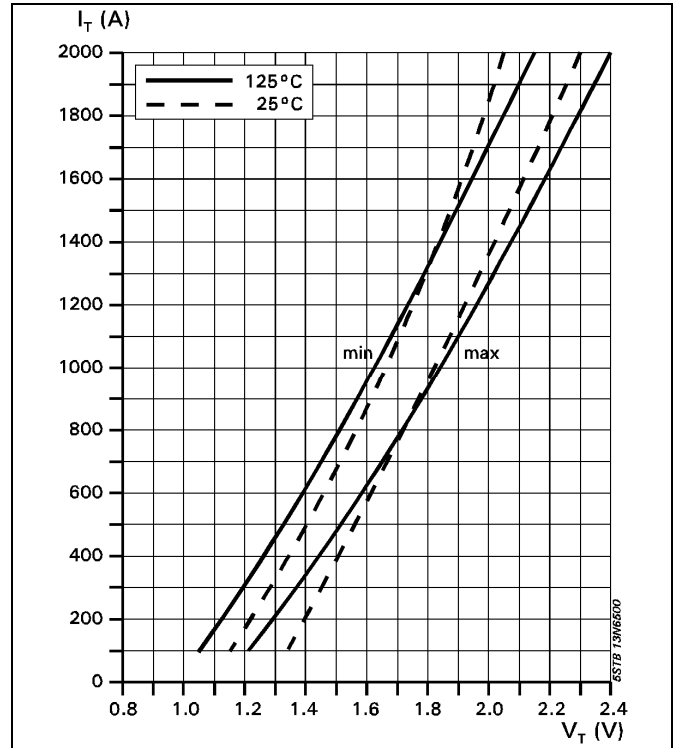


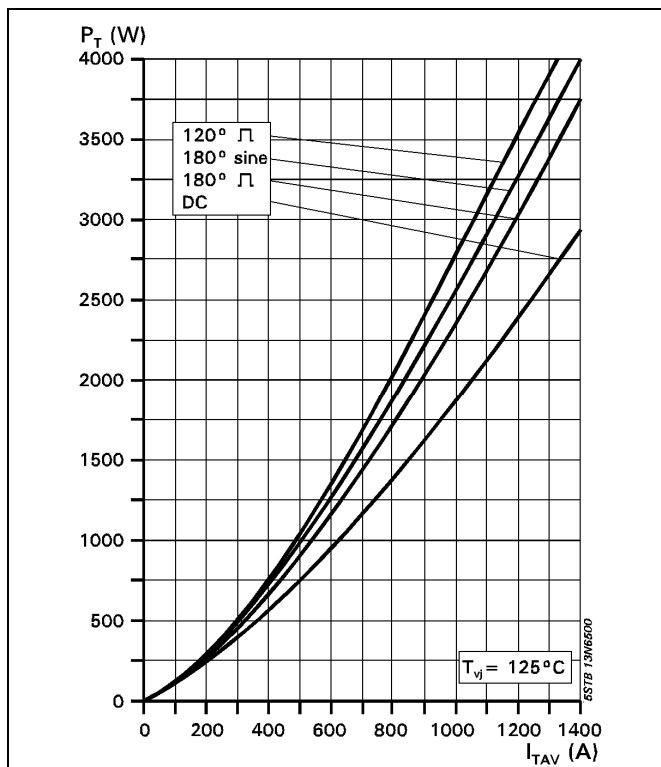
Fig. 1 Transient thermal impedance (junction-to-case) vs. time



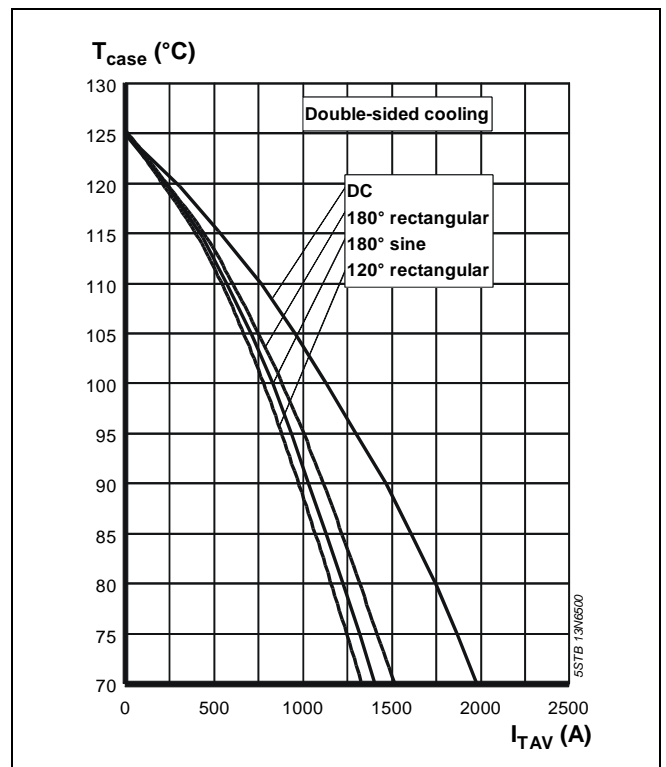
**Fig. 2** On-state characteristics,  $T_j = 125^\circ\text{C}$ , 10ms half sine



**Fig. 3** On-state voltage characteristics



**Fig. 4** On-state power dissipation vs. mean on-state current. Switching losses excluded.



**Fig. 5** Max. permissible case temperature vs. mean on-state current. Switching losses ignored.

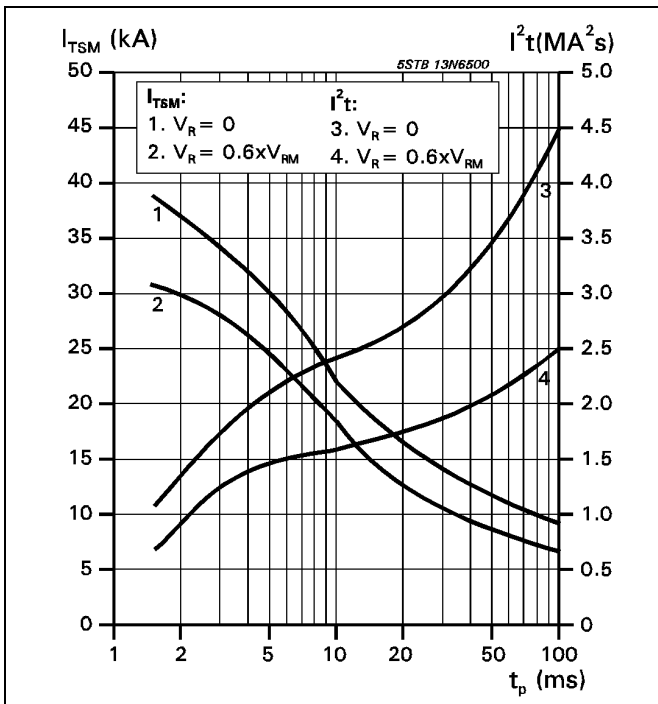


Fig. 6 Surge on-state current vs. pulse length. Half-sine wave.

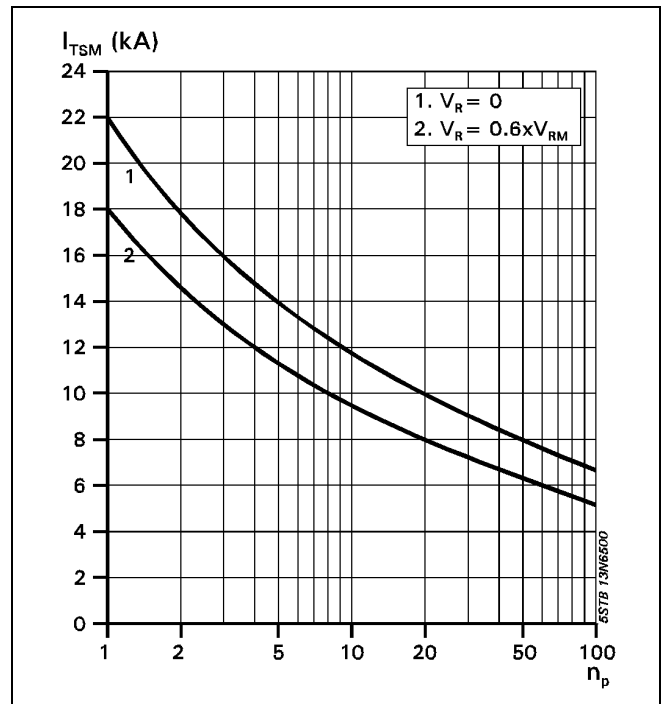


Fig. 7 Surge on-state current vs. number of pulses. Half-sine wave, 10 ms, 50Hz.

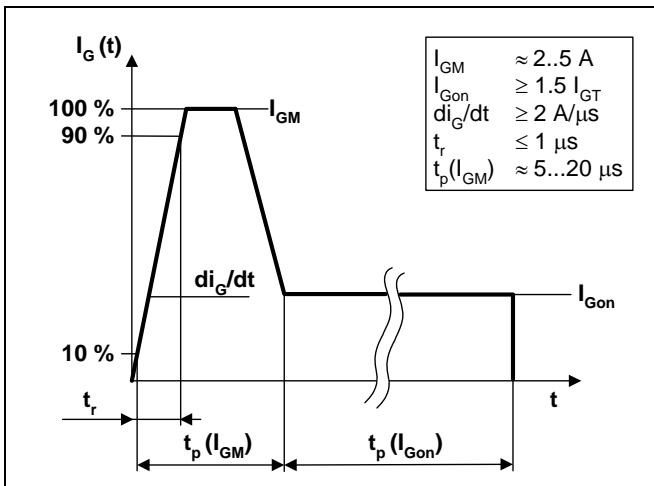


Fig. 8 Recommended gate current waveform

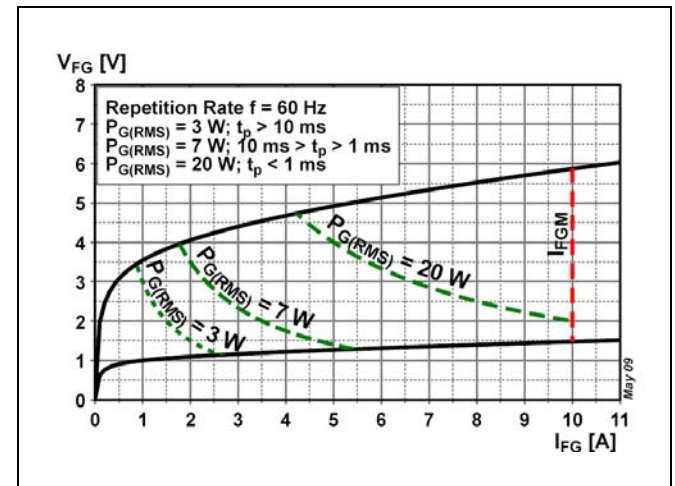


Fig. 9 Max. peak gate power loss

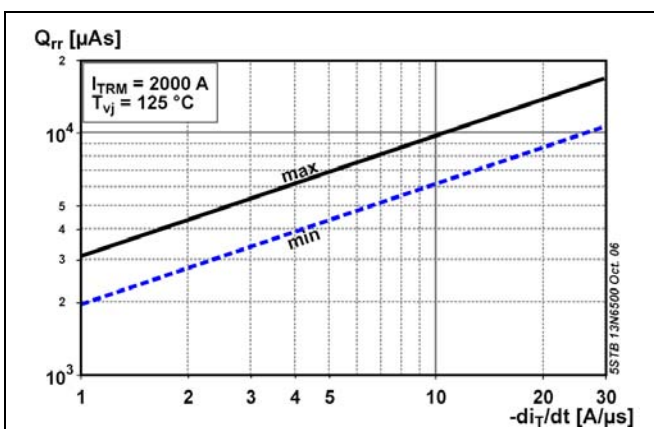


Fig. 10 Reverse recovery charge vs. decay rate of on-state current

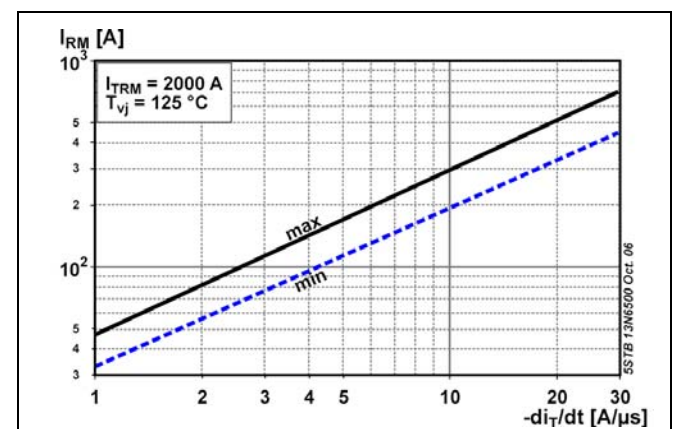


Fig. 11 Peak reverse recovery current vs. decay rate of on-state current

# Turn-on and Turn-off losses

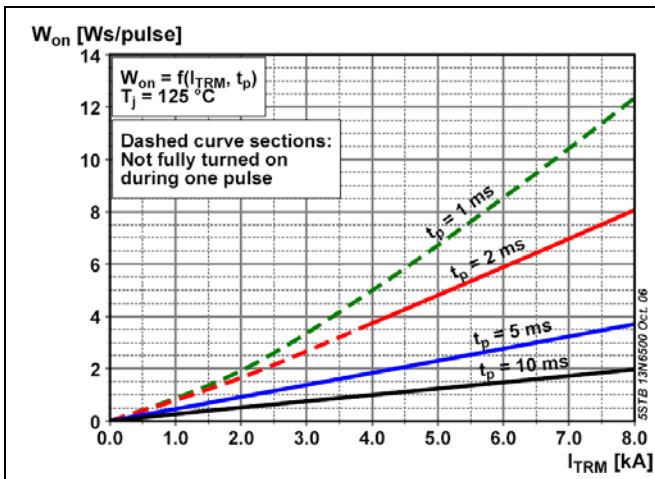


Fig. 12 Turn-on energy, half sinusoidal waves

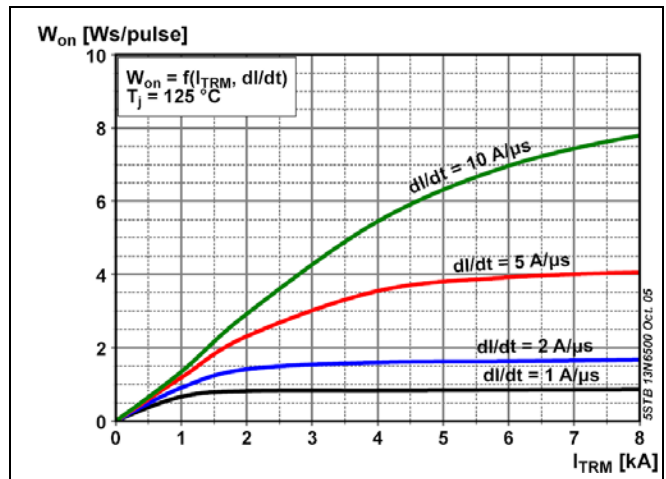


Fig. 13 Turn-on energy, rectangular waves

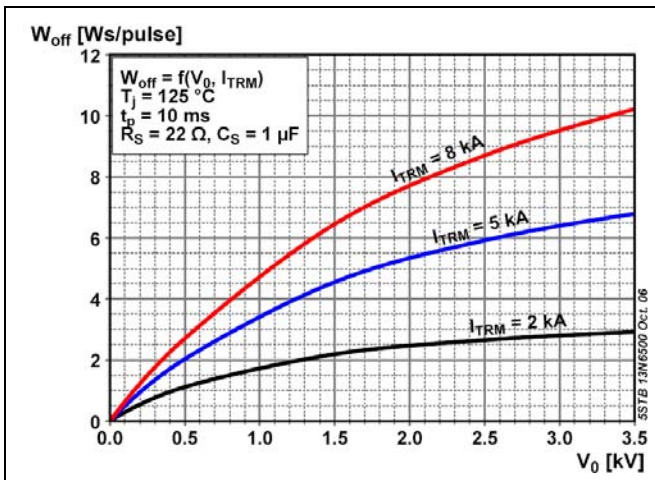


Fig. 14 Turn-off energy, half sinusoidal waves

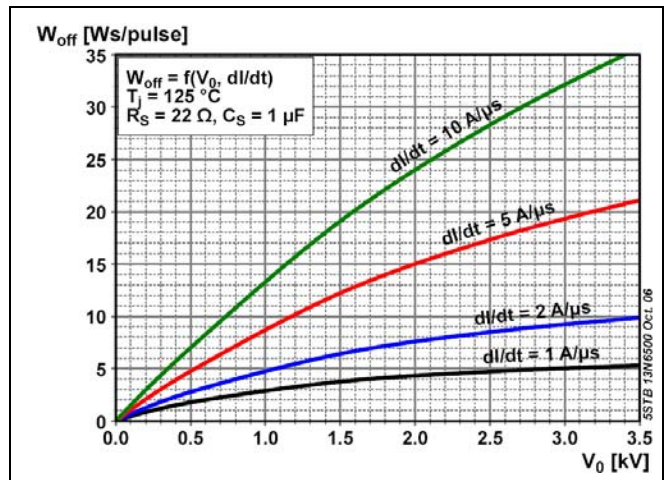


Fig. 15 Turn-off energy, rectangular waves

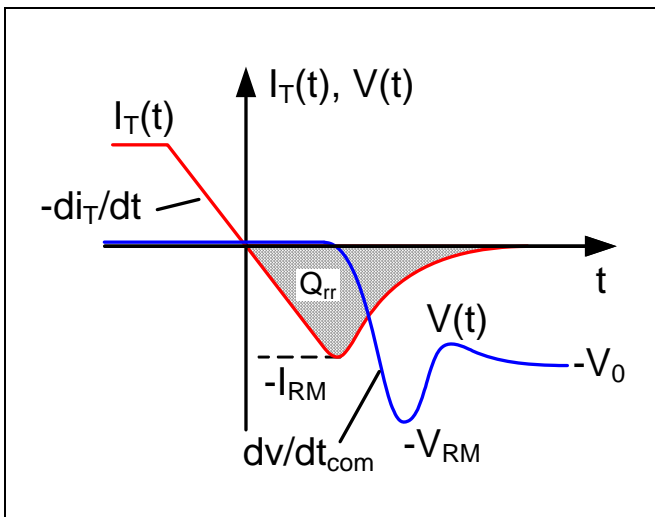


Fig. 16 Current and voltage waveforms at turn-off

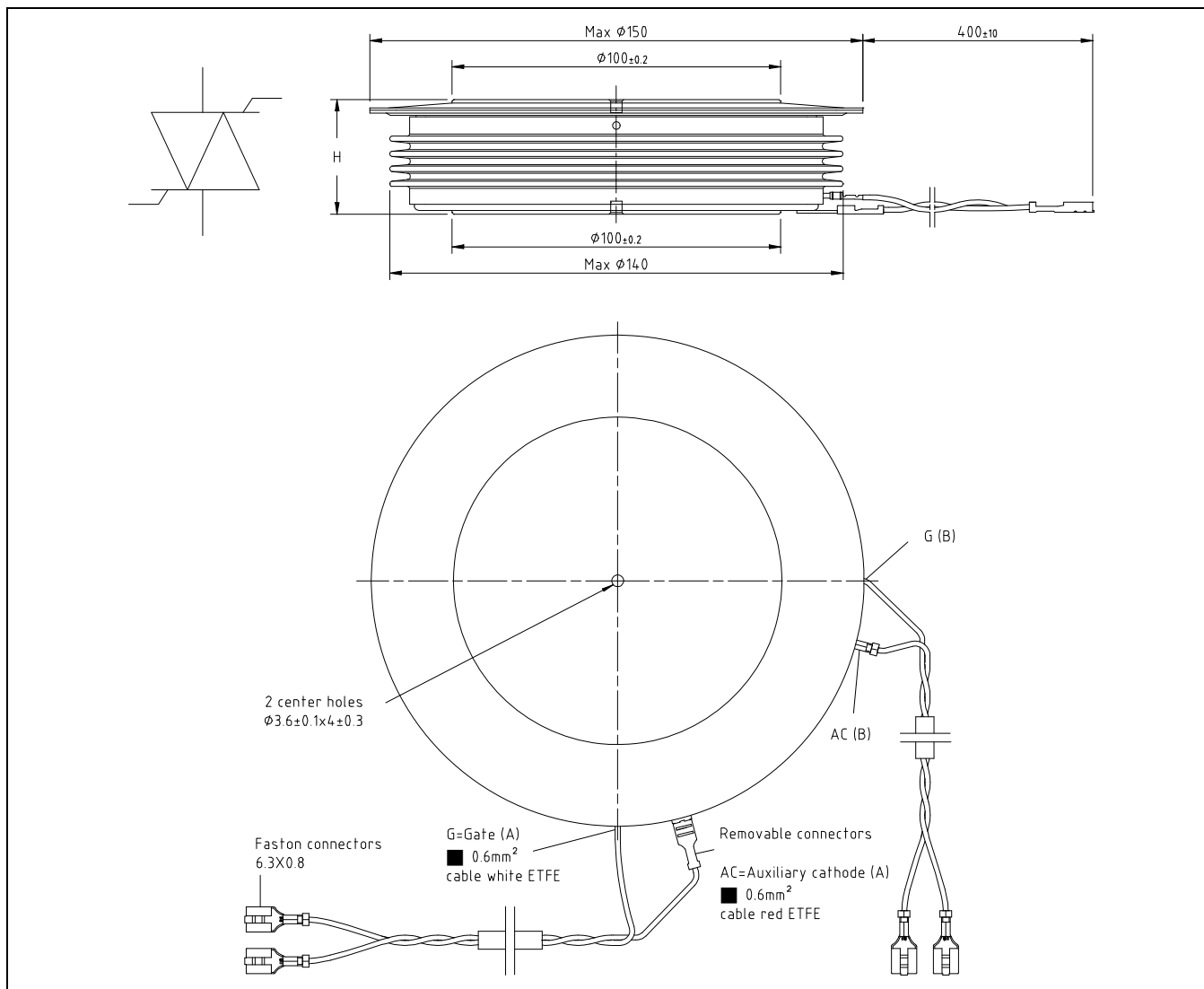
**Total power loss for repetitive waveforms:**

$$P_{TOT} = P_T + W_{on} \cdot f + W_{off} \cdot f$$

where

$$P_T = \frac{1}{T} \int_0^T I_T \cdot V_T(I_T) dt$$

Fig. 17 Relationships for power loss



**Fig. 18** Device Outline Drawing

### Related documents:

|           |   |
|-----------|---|
| 5SYA 2020 | Design of RC-Snubber for Phase Control Applications   |
| 5SYA 2049 | Voltage definitions for phase control thyristors and diodes   |
| 5SYA 2051 | Voltage ratings of high power semiconductors  |
| 5SYA 2034 | Gate-Drive Recommendations for PCT's  |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors   |
| 5SZK 9104 | Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE available on request, please contact factory        |
| 5SZK 9105 | Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION available on request, please contact factory |

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

**ABB Switzerland Ltd, Semiconductors reserves the right to change specifications without notice.**



**ABB Switzerland Ltd**  
**Semiconductors**  
 Fabrikstrasse 3  
 CH-5600 Lenzburg, Switzerland

Doc. No. 5SYA1035-04 Aug. 10

Telephone +41 (0)58 586 1419  
 Fax +41 (0)58 586 1306  
 Email [abbsem@ch.abb.com](mailto:abbsem@ch.abb.com)  
 Internet [www.abb.com/semiconductors](http://www.abb.com/semiconductors)

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [SCRs category](#):*

*Click to view products by [ABB manufacturer](#):*

Other Similar products are found below :

[NTE5428](#) [T1500N16TOF VT](#) [T660N22TOF](#) [T720N18TOF](#) [T880N14TOF](#) [T880N16TOF](#) [TT162N16KOF-A](#) [TT162N16KOF-K](#)  
[TT330N16AOF](#) [VS-22RIA20](#) [VS-2N685](#) [057219R](#) [T1190N16TOF VT](#) [T1220N22TOF VT](#) [T201N70TOH](#) [T700N22TOF](#) [TT250N12KOF-K](#)  
[VS-110RKI40](#) [NTE5427](#) [NTE5442](#) [T2160N28TOF VT](#) [TT251N16KOF-K](#) [VS-22RIA100](#) [VS-16RIA40](#) [TD250N16KOF-A](#) [VS-ST110S16P0](#)  
[T930N36TOF VT](#) [T2160N24TOF VT](#) [T1190N18TOF VT](#) [T1590N28TOF VT](#) [2N1776A](#) [T590N14TOF](#) [NTE5375](#) [NTE5460](#) [NTE5481](#)  
[NTE5504](#) [NTE5512](#) [NTE5514](#) [NTE5518](#) [NTE5519](#) [NTE5529](#) [NTE5553](#) [NTE5555](#) [NTE5557](#) [NTE5567](#) [NTE5570](#) [NTE5572](#) [NTE5574](#)  
[NTE5576](#) [NTE5579](#)